Parameters

HRSS

MEMS strain sensor

Sensor Thickness	350 μm
Connection to electronics	Flex PCB - FPC 12pins connector
Measuring principle	MEMS vibrating wire
Operation principle	Low noise closed loop readout
Applicable bonding materials	Cold/hot curing epoxy adhesive
Active gauge length	0.30 mm (0,012")
Range (nominal)	1000 με
Resonance frequency	300 - 400 kHz
Resolution	0.004 με @ 100Hz
	0.00035 με @ 10Hz
Accuracy	±0.5% FS
Measuiring bandwidth (0.5/T _{acq})	5 kHz
Embedded temperature sensor resolution	± 0.01°C
Embedded temperature sensor accuracy	± 0.3°C
Power supply	5 ÷ 17 V
Output	Digital floats
	(Strain and Temperature)
Comunication protocol	USB, CAN FD, HS-CAN,
	customizable
Sensor thermal expansion coefficient	3 x 10 ⁻⁶ / °C



HRSS

High Resolution Strain Sensor



Sensing Beyond the limits

Simplify real-time measurement of your products and create new business opportunities...

> **Innovative MEMS microsensors** for High-Resolution, Non-Invasive Diagnostics and **Prognostics**



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Via P.Gobetti 101, Bologna (BO), Italia

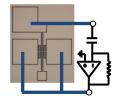
High-resolution, low power strain sensors based on MEMS resonators

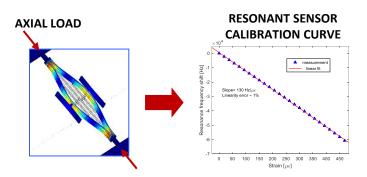
MEMS sensor (HRSS) obtained by top/down micromachining of monocrystalline silicon

A resonant micromechanical device serves as a high-resolution strain sensor, exploiting the correlation between its mechanical resonance frequency and the applied force along its axis.

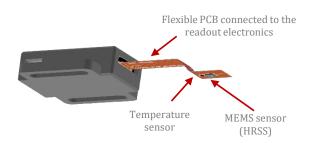
Under such conditions, this frequency undergoes significant variations, analogous to a guitar string changing its tone when tuned. The oscillation frequency of a closed-loop circuit containing the resonator is utilized as sensing signal for strain.

OSCILLATOR SIMPLIFIED CIRCUIT

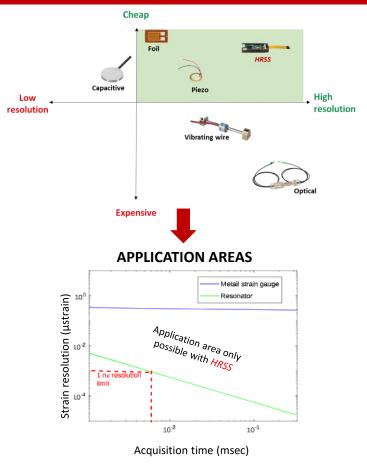




STRAIN SENSOR PACKAGE

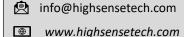


COMPARISON WITH **COMMERCIAL STRAIN GAUGE**



HRSS sensor can measure:

- Strain
- Pressure
- **Force**
- Weight
- Our microsensors offer unparalleled **Torque**
- precision and bandwidth, enabling and more...
- real-time fast measurement



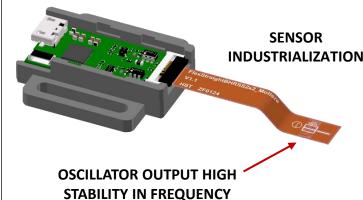


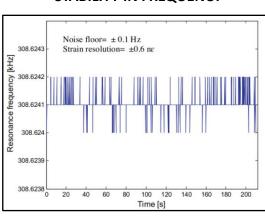
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PRODUCTION CAPABILITY



fabrication process is implemented on 4-inch Silicon on Insulator (SOI) technology. A sensor chip size of 2x2.5 mm² ensures a yield for wafers exceeding 1000. Present HST production capabilities reach 20,000 sensors per year, with plans to scale up to 200,000 within the next three years.







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